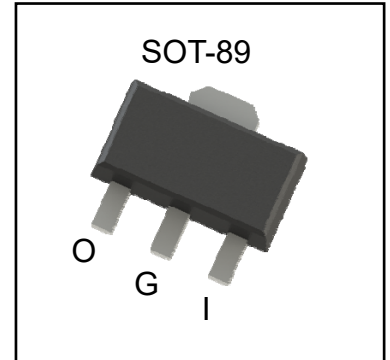


**30V 100mA Low Dropout Voltage Regulator**

# ICR78LXXM3



## Description

The ICR78LXXM3 positive regulators are available with 5V and 3.3V fixed output voltages, making them useful in a wide range of applications. Used as a Zener diode and resistor combination replacement, ICR78LXXM3 usually provides an effective output impedance improvement of two orders of magnitude and lower quiescent current. These regulators can provide local on-card regulation, eliminating distribution problems associated with single point regulation. The available voltages allows ICR78LXXM3 to be used in logic systems, instrumentation, HiFi, and other solid state electronic equipments.

Each type employs internal current limiting, thermal shut-down and safe operating area protection, making it essentially indestructible. If adequate heat sinking is provided, the regulator can deliver over 100mA output current.

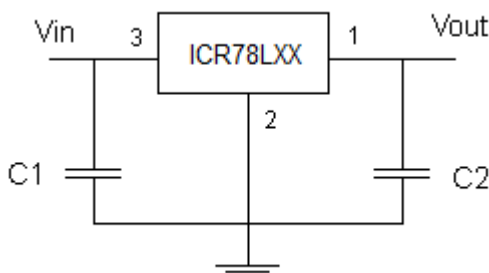
## Features:

- $V_{IN}$  range up to 30V
- Output voltage tolerance of  $\pm 5\%$  over the temperature range
- Output current of 100mA
- Output transistor safe area protection
- Internal thermal overload protection
- Internal short-circuit current limit
- Pb-free lead plating and halogen-free package

## Applications:

- Battery chargers
- Portable instrumentation
- LED lighting
- Low wattage power supplies

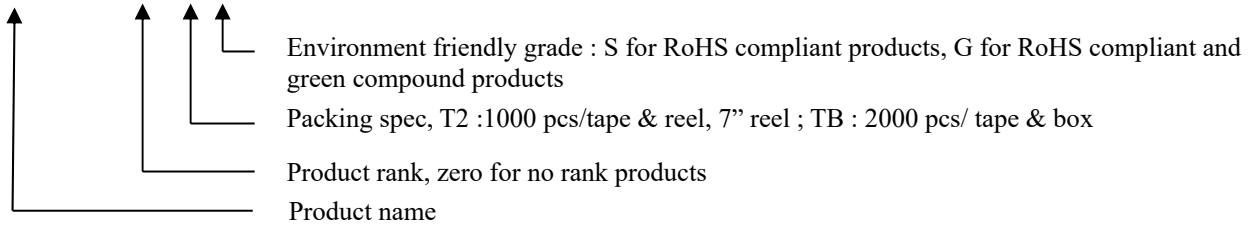
## Typical Application Circuit:



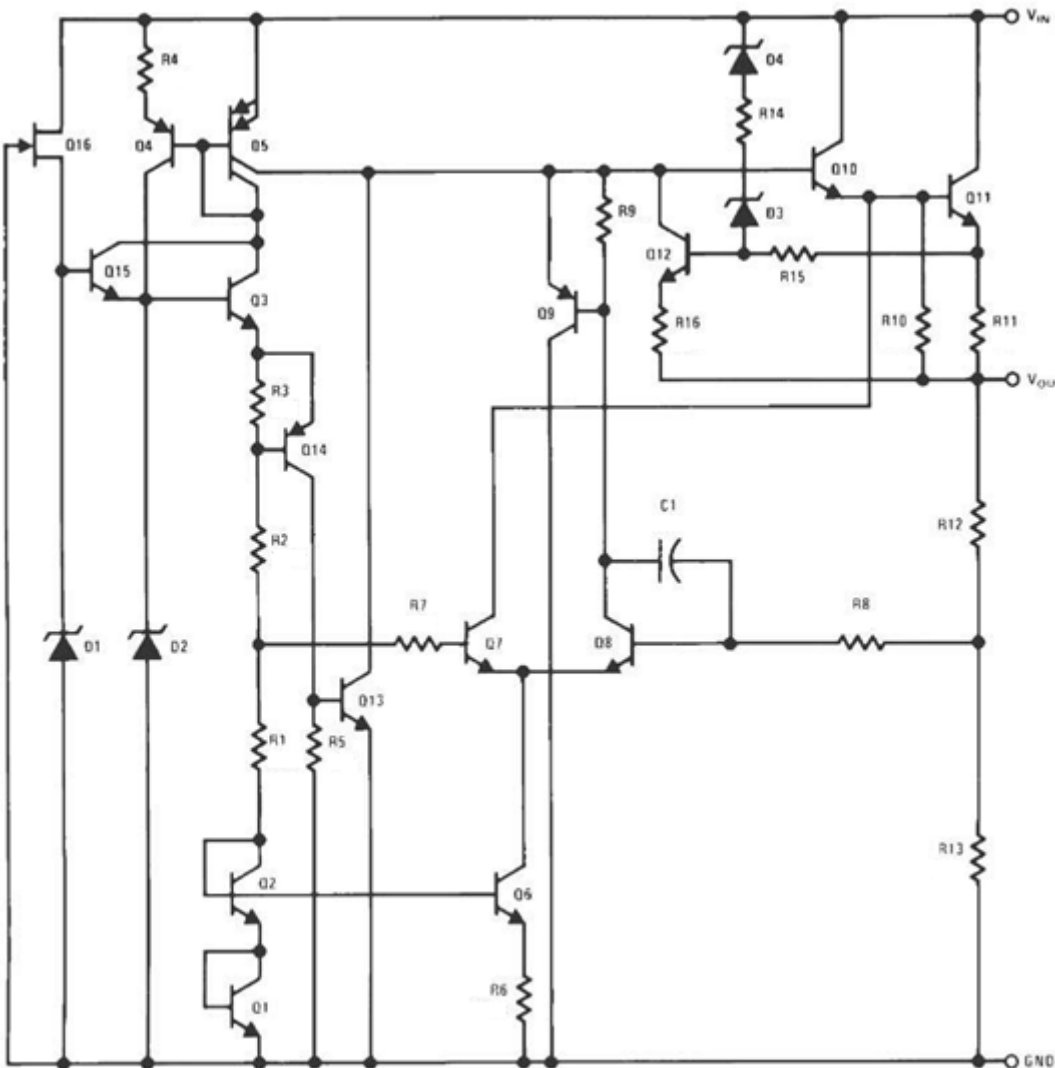
Note : C1 and C2 are required if regulator is located far from power supply filter and load, or oscillation may induced on the loop.

**Ordering Information**

Device	Output Voltage Tolerance	Package	Shipping
ICR78LXXM3-A-T2-G	±3%	SOT-89 (Pb-free lead plating and halogen-free package)	1000 pcs / Tape & Reel
ICR78LXXM3-B-T2-G	±5%		



**Function Block Diagram:**





### Absolute Maximum Ratings

Parameter	Ratings	Unit
Input Voltage	30	V
Output Current	100	mA
Operating Junction Temperature Range	-40 ~ +125	°C
Storage Temperature Range	-65 ~ +150	°C
Power Dissipation	500 (Note)	mW

Note : When mounted on minimum pad size and tested in free air condition, without heat sinking.

### Electrical Characteristics

#### ICR78L33M3

( $V_{in}=10V$ ,  $I_o=40mA$ ,  $T_j=25^{\circ}C$ ,  $C_{in}=0.33\mu F$ ,  $C_{out}=0.1\mu F$ , unless otherwise noted) (Note 1)

Symbol	Parameter	Min	Typ	Max	Conditions	Units
$V_o$	Output Voltage	3.20	3.3	3.40	$V_{in}=10V$ , $I_o=40mA$ , $T_j=25^{\circ}C$	V
		3.13		3.47		
		3.13	-	3.47	$7V \leq V_{in} \leq 20V$ , $1mA \leq I_o \leq 40mA$ $V_{in}=10V$ , $1mA \leq I_o \leq 70mA$ (Note 2)	
$\Delta V_o$	Line Regulation	-	12	30	$7V \leq V_{in} \leq 20V$	mV
		-	10	25	$8V \leq V_{in} \leq 20V$	
$\Delta V_o$	Load Regulation	-	20	50	$1mA \leq I_o \leq 100mA$	mV
		-	10	25	$1mA \leq I_o \leq 40mA$	
$I_Q$	Quiescent Current	-	0.3	1.2	$T_j=25^{\circ}C$ , $V_{in}=10V$ , $I_o=0mA$	mA
$\Delta I_Q$	Quiescent Current Change	-	-	0.2	$8V \leq V_{in} \leq 20V$	mA
		-	-	0.1	$1mA \leq I_o \leq 40mA$	
$V_n$	Output Noise Voltage	-	32	-	$10Hz \leq f \leq 100KHz$	$\mu V$
$\Delta V_{in} / \Delta V_{out}$	Ripple Rejection	75	84	-	$8V \leq V_{in} \leq 20V$ , $f=120Hz$	dB
$\Delta V_o / \Delta T_j$	Temperature Stability	-	0.2	0.5	$I_o=5mA$ , $0^{\circ}C \leq T_j \leq 125^{\circ}C$	$mV/^{\circ}C$
$V_D$	Dropout Voltage	-	0.8	-	$I_o=40mA$	V



ICR78L05M3

(Vin=10V, Io=40mA, Tj=25°C, Cin=0.33uF, Cout=0.1uF ,unless otherwise noted) (Note 1)

Symbol	Parameter	Min	Typ	Max	Conditions	Units
Vo	A-rank(3%)	4.85	5	5.15	Vin=10V, Io=40mA, Tj=25°C	V
	B-rank(5%)	4.75		5.25		
		Output Voltage	4.75	-	5.25	
ΔVo	Line Regulation	-	12	30	7V≤Vin≤20V	mV
		-	10	25	8V≤Vin≤20V	
ΔVo	Load Regulation	-	20	50	1mA≤Io≤100mA	mV
		-	10	25	1mA≤Io≤40mA	
IQ	Quiescent Current	-	0.3	1.2	Tj=25°C, Vin=10V, Io=0mA	mA
ΔIQ	Quiescent Current Change	-	-	0.2	8V≤Vin≤20V	mA
		-	-	0.1	1mA≤Io≤40mA	
Vn	Output Noise Voltage	-	32	-	10Hz≤f≤100KHz	μV
ΔVin / ΔVout	Ripple Rejection	75	84	-	8V≤Vin≤20V, f=120Hz	dB
ΔVo/ΔTj	Temperature Stability	-	0.2	0.5	Io=5mA, 0°C ≤Tj≤125°C	mV/°C
VD	Dropout Voltage	-	0.8	-	Io=40mA	V

- Note : 1. The maximum steady state usable output current is dependent on input voltage, heat sinking, lead length of the package and copper of PCB. The data above represent pulse test conditions with junction temperatures specified at the initial of test.
2. Power dissipation<0.5W

**Typical Characteristics**

@  $V_{IN}=10V$ ,  $I_{OUT}=40mA$ ,  $C_{IN}=0.33\mu F$ ,  $C_{OUT}=0.1\mu F$ ,  $T_J=25^\circ C$ , unless otherwise specified

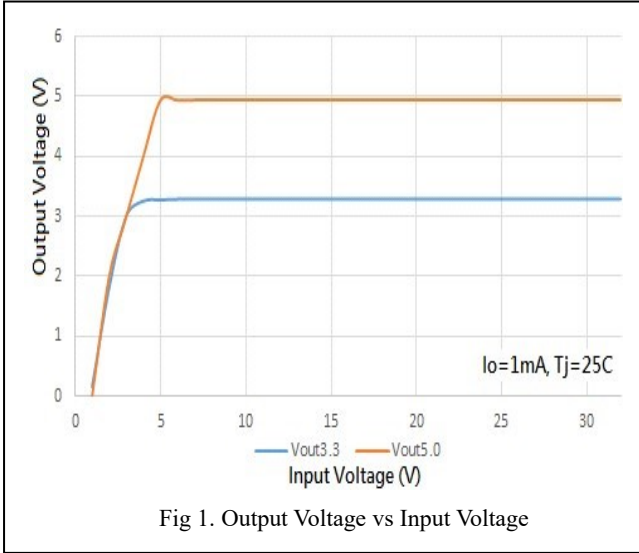


Fig 1. Output Voltage vs Input Voltage

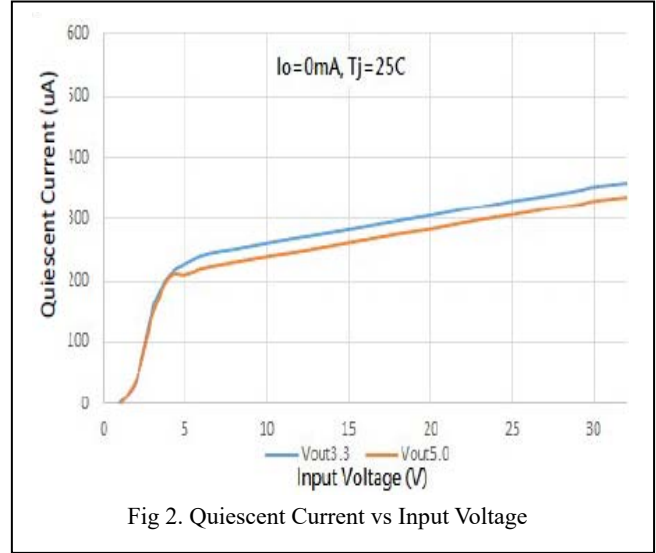


Fig 2. Quiescent Current vs Input Voltage

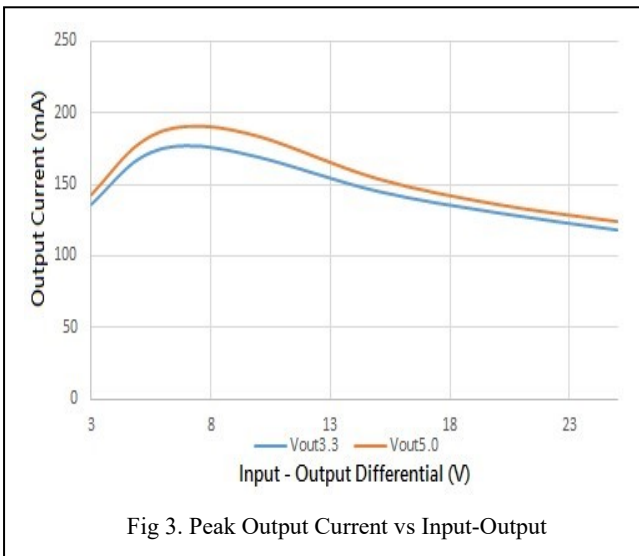


Fig 3. Peak Output Current vs Input-Output

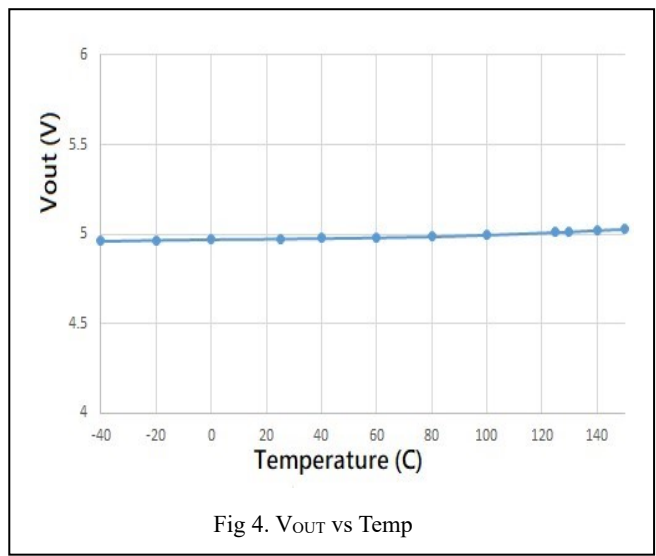


Fig 4.  $V_{OUT}$  vs Temp

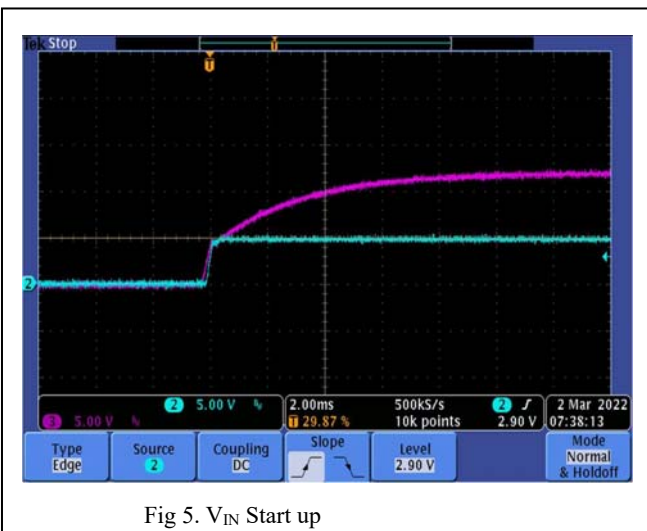


Fig 5.  $V_{IN}$  Start up

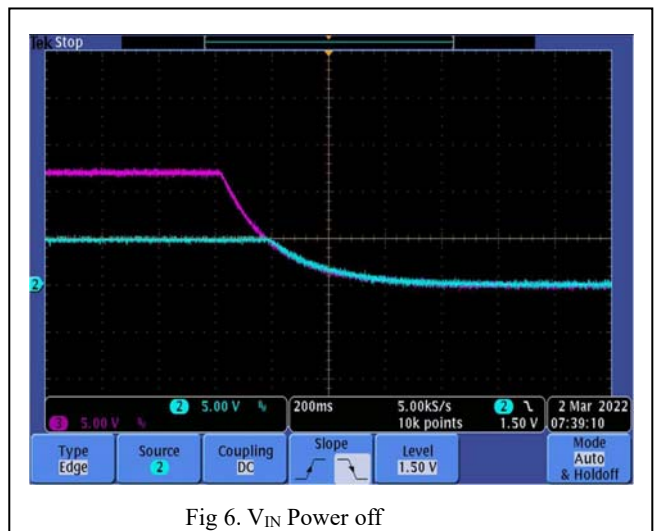


Fig 6.  $V_{IN}$  Power off

**Typical Characteristics (Cont.)**

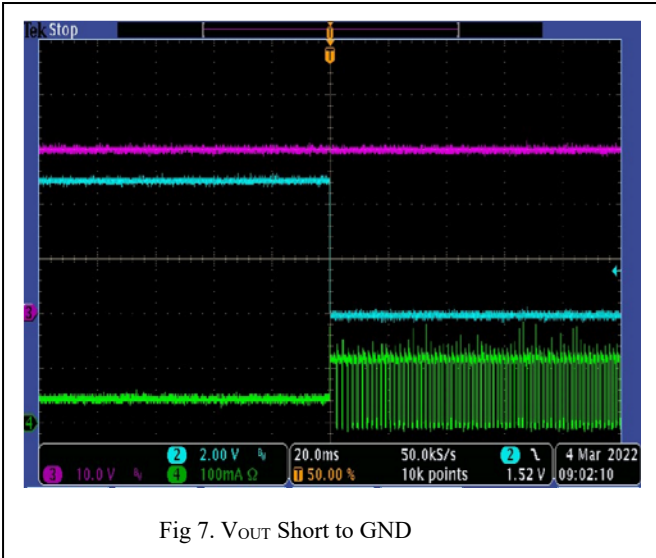


Fig 7.  $V_{OUT}$  Short to GND

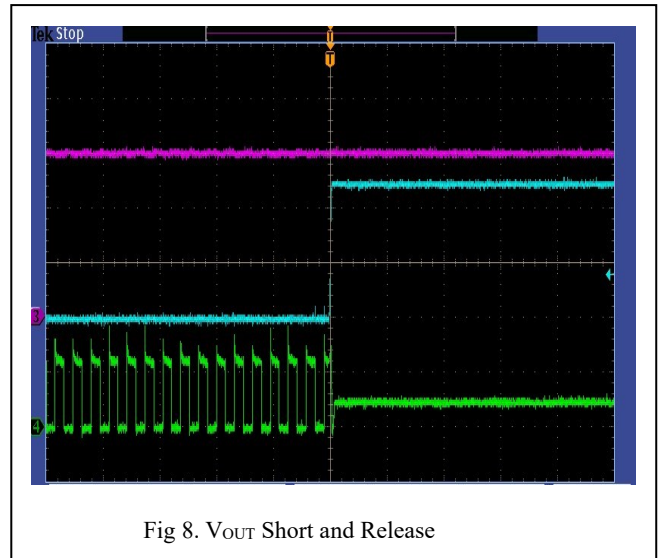


Fig 8.  $V_{OUT}$  Short and Release

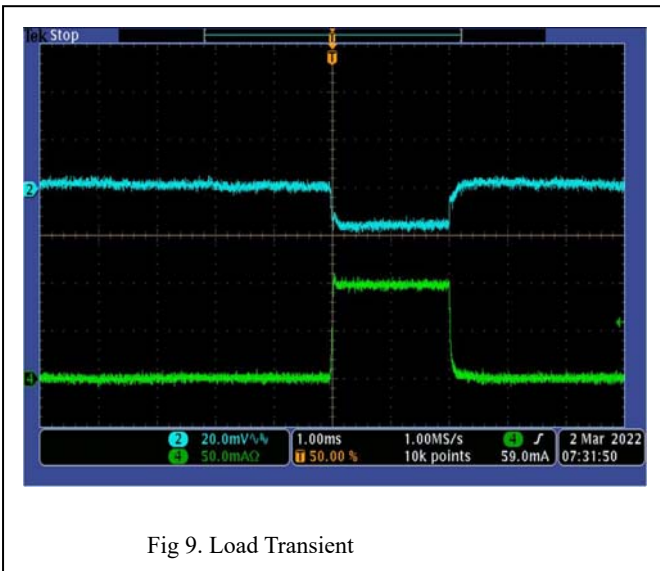


Fig 9. Load Transient

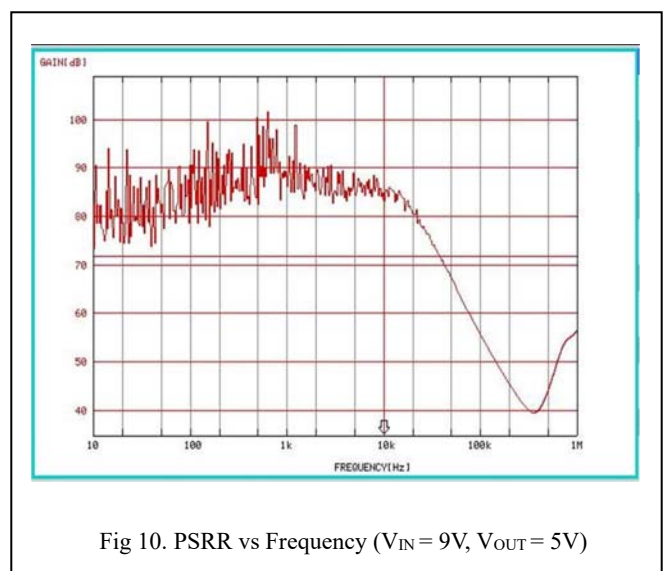
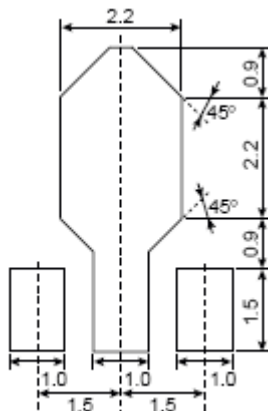


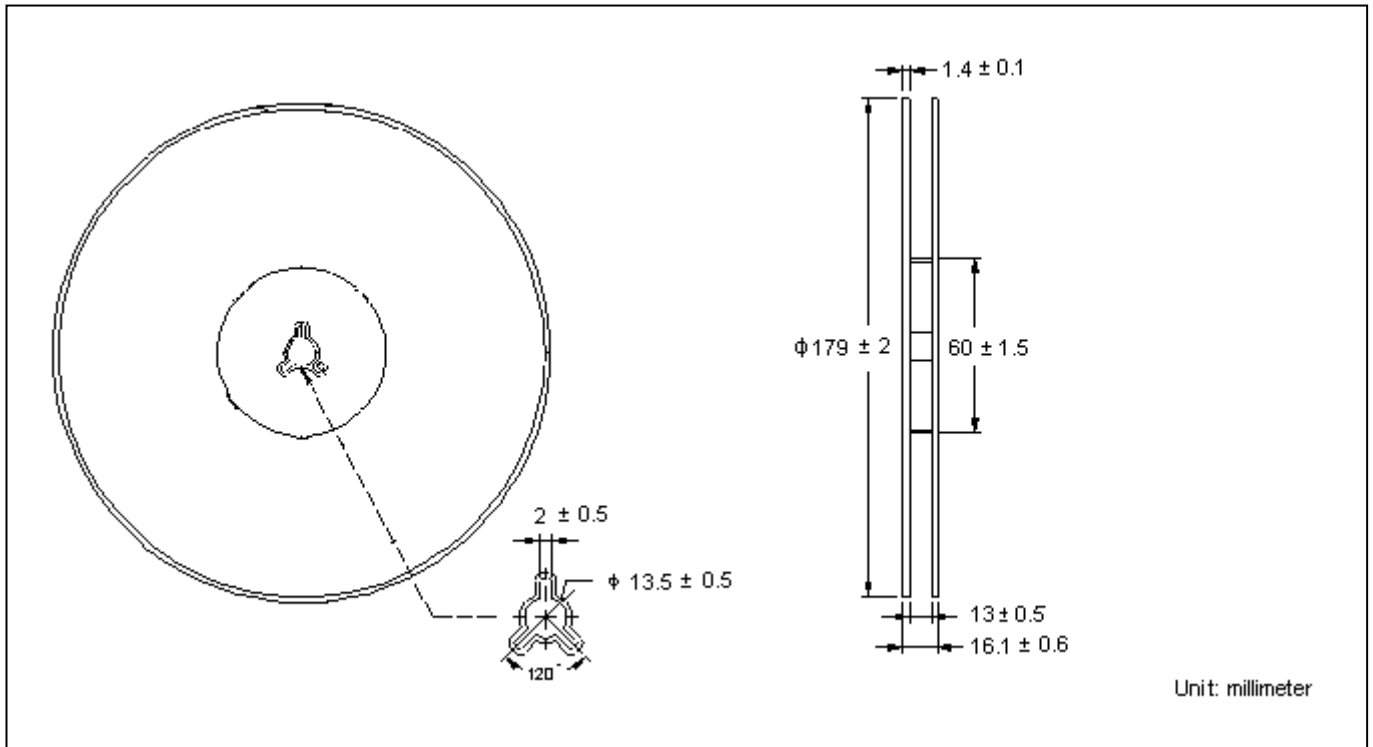
Fig 10. PSRR vs Frequency ( $V_{IN} = 9V, V_{OUT} = 5V$ )

**Recommended Soldering Footprint**

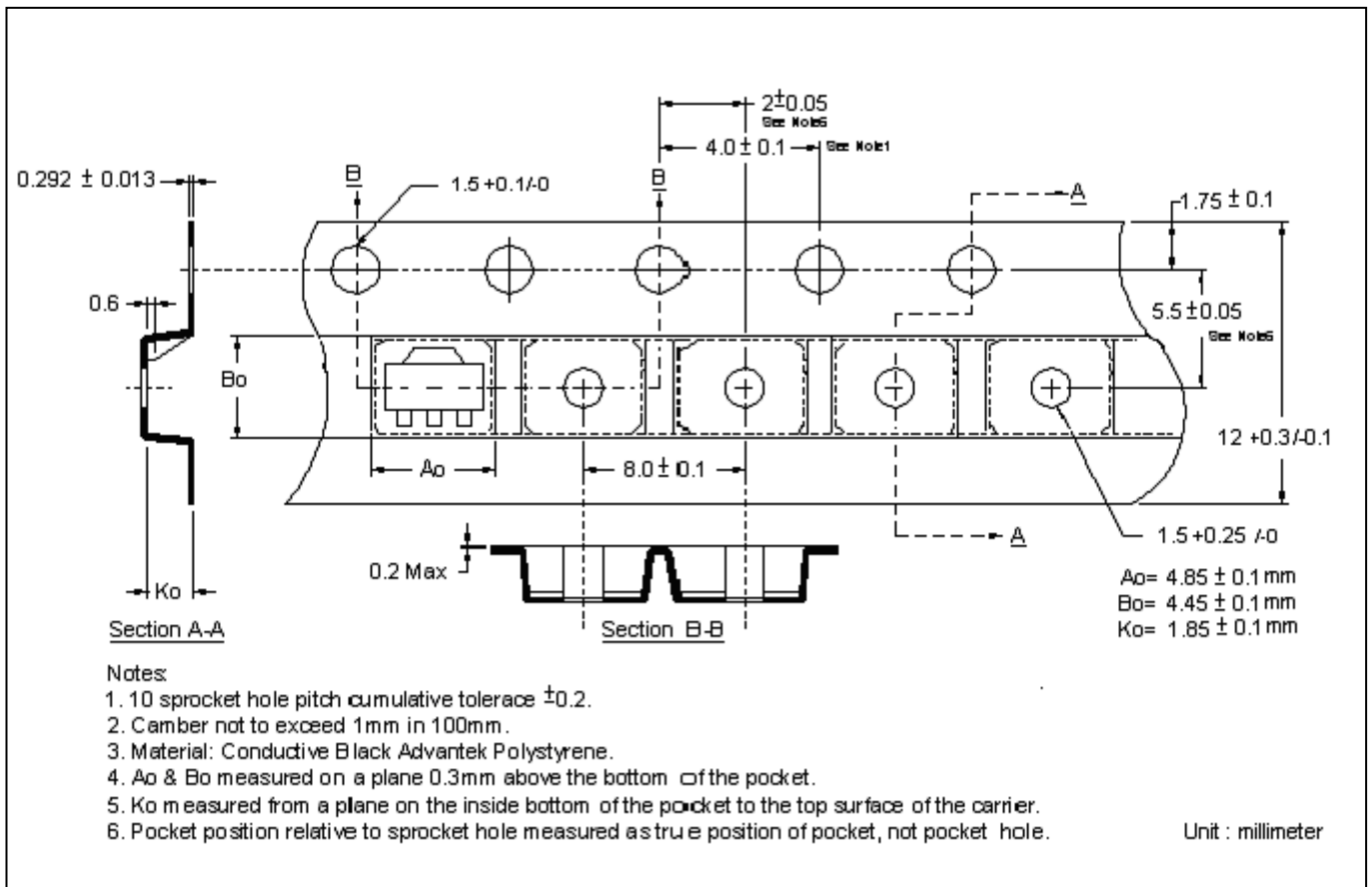


unit : mm

**Reel Dimension**



**Carrier Tape Dimension**

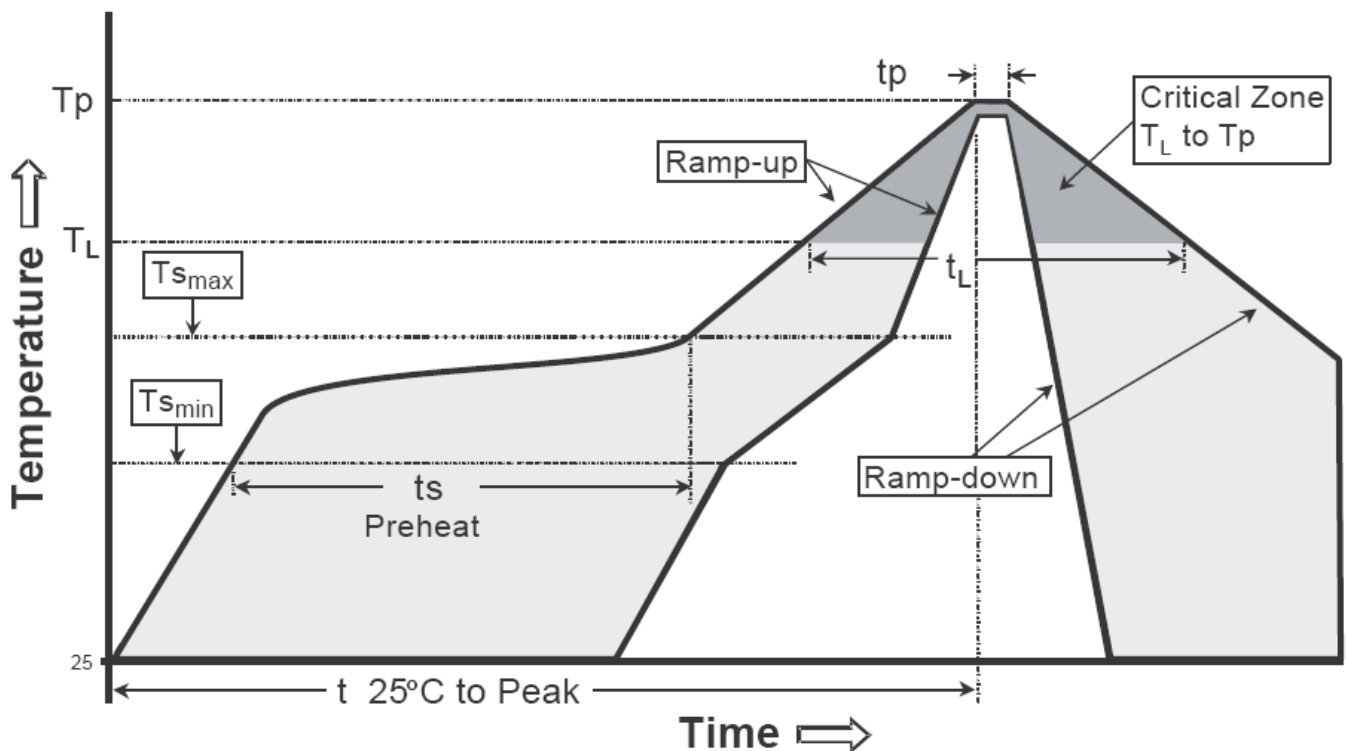




**Recommended wave soldering condition**

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

**Recommended temperature profile for IR reflow**

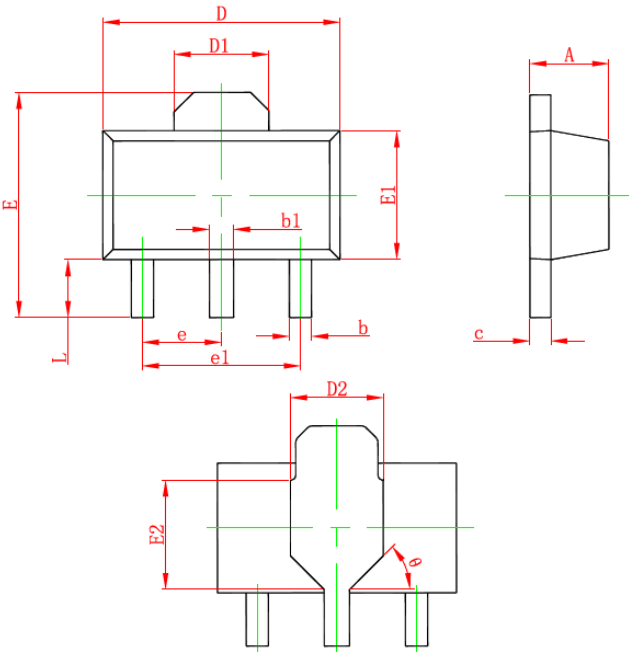


Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (T <sub>smax</sub> to T <sub>p</sub> )	3°C/second max.	3°C/second max.
Preheat		
-Temperature Min(T <sub>s min</sub> )	100°C	150°C
-Temperature Max(T <sub>s max</sub> )	150°C	200°C
-Time(t <sub>s min</sub> to t <sub>s max</sub> )	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (T <sub>L</sub> )	183°C	217°C
- Time (t <sub>L</sub> )	60-150 seconds	60-150 seconds
Peak Temperature(T <sub>p</sub> )	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

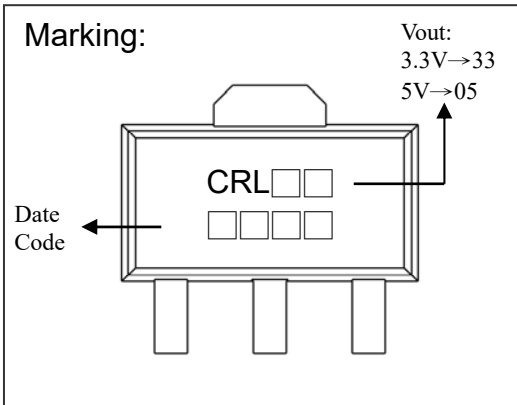
Note : All temperatures refer to topside of the package, measured on the package body surface.



**SOT-89 Dimension**



**Marking:**



**Style:** Pin 1. Vout 2. GND 3. Vin

Date Code(counting from left to right) :  
 1<sup>st</sup> code: year code, the last digit of Christian year  
 2<sup>nd</sup> code : month code, Jan→A, Feb→B, Mar→C,  
 Apr→D, May→E, Jun→F, Jul→G, Aug→H,  
 Sep→J, Oct→K, Nov→L, Dec→M  
 3<sup>rd</sup> and 4<sup>th</sup> codes : production serial number, 01~99

**3-Lead SOT-89 Plastic Surface Mounted Package  
 CYS Package Code: M3**

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.055	0.063	1.40	1.60	E	0.155	0.167	3.94	4.25
b	0.013	0.020	0.32	0.52	E1	0.091	0.102	2.30	2.60
b1	0.016	0.023	0.40	0.58	E2	0.075 REF.		1.90 REF.	
c	0.014	0.017	0.35	0.44	e	0.060 TYP.		1.50 TYP.	
D	0.173	0.181	4.40	4.60	e1	0.118 TYP.		3.00 TYP.	
D1	0.061 REF.		1.55 REF.		L	0.035	0.047	0.90	1.20
D2	0.069 REF.		1.75 REF.		θ	45°		45°	

**Notes:** 1.Controlling dimension: millimeters.  
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.  
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

**Material:**

- Lead: Pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.

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